
Mask Set Errata for 68HC912DT128A, Mask 0M63Z

Introduction

This mask set errata applies to this 68HC912DT128A MCU mask set:

- 0M63Z

MCU Device Mask Set Identification

The mask set is identified by a 5-character code consisting of a version number, a letter, two numerical digits, and a letter, for example 2J88Y. All standard devices are marked with a mask set number and a date code.

MCU Device Date Codes

Device markings indicate the week of manufacture and the mask set used. The date is coded as four numerical digits where the first two digits indicate the year and the last two digits indicate the work week. For instance, the date code "0401" indicates the first week of the year 2004.

MCU Device Part Number Prefixes

Some MCU samples and devices are marked with an SC, PC, or XC prefix. An SC prefix denotes special/custom device. A PC prefix indicates a prototype device which has undergone basic testing only. An XC prefix denotes that the device is tested but is not fully characterized or qualified over the full range of normal manufacturing process variations. After full characterization and qualification, devices will be marked with the MC or SC prefix.

Errata number	Module affected	Description
AR_526	IIC	SCL divider has an extra clock at 8Mhz bus frequency

IIC Bus Frequency

Errata Number: HC12_AR_526

Description

At maximum system frequency, the IIC bus rate slows down as much as 5%.

Workaround

Communication rate will be adjusted automatically to slower rate.

Errata number	Module affected	Description
AR_527	INT	Disabling interrupt with I mask bit clear can cause SWI

Disabling Interrupts

Errata Number: HC12_AR_527

Description

If the source of an interrupt is taken away by disabling the interrupt without setting the I mask bit in the CCR, an SWI interrupt may be fetched instead of the vector for the interrupt source that was disabled.

Workaround

Before disabling an interrupt using a local interrupt control bit, set the I mask bit in the CCR.

Errata number	Module affected	Description
AR_548	IIC	Disabling IIC can glitch and corrupt IIC bus

Disabling IIC

Errata Number: HC12_AR_548

Description

If the IIC module is disabled by clearing the IBEN bit in IBCR register, the SDA and SCL lines in the IIC bus will glitch to zero if PORTIB bits 6 and 7 are zero.

Workaround

Set PORTIB bits 6 and 7 to one prior to clearing IBEN bit in IBCR register.

Errata number	Module affected	Description
AR_573	IIC	IIC hold both SCL and SDA line low when IBB bit is not busy

SCL Line During Start Signal

Errata Number: HC12_AR_573

Description

If SCL line is pulled low when generating a start signal the device will lock up.

Workaround

After trying to generate a START signal and neither the IBB nor IBAL bits are set after several cycles, the IIC should be disabled and reenabled with the IBEN bit.

Errata number	Module affected	Description
AR_593	CGM	Operation with 16MHz quartz crystals is not recommended

Operation with 16MHz Quartz Crystals

Errata Number: HC12_AR_593

Description

The variation of operational parameters within a given crystal part number may include a distribution of parts that present impedance conditions at startup that will not function with the current design of the CGM. While typical parts may function correctly, problems may be seen in actual production runs.

Workaround

Quartz crystal operation should be restricted to maximum of 8 MHz. Workarounds include:

- Use an 8 MHz (or slower) oscillator and generate higher bus frequencies using the PLL module.
- Use alternative ceramic resonator.
- Where minimal clock jitter is critical, use external “brick” quartz oscillator module.

Errata number	Module affected	Description
AR_627	CGM	CPU does not start up correctly after switching to ext crystal

CPU Start-up with External Crystal

Errata Number: HC12_AR_627

Description

The device can prematurely indicate that the oscillator has stabilized releasing the part from Limp Home clock mode to the oscillator clock mode with an unstable oscillator. This can cause unpredictable behavior of the MCU. This situation can arise with short external power-on reset periods and / or crystal oscillator circuits that exhibit slow startup characteristics. If the PLL is not being used (Vddpll connected to Vss) Limp Home mode is disabled and this issue does not apply.

All customers should review any applications based on the referenced devices. If the crystal clock is stabilized before the external RESET line is released and the customer is not using stop mode (pseudo-stop is not affected) then there is no problem. If the clock is not stable when external RESET is released then they should contact Motorola for consultation.

Common practice for the start up mode of operation of HC12 microcontrollers is for the external RESET line to be held active until such time as the crystal has stabilized at its operating frequency. On release of the external RESET line and when the WCR (counter register) reaches a count of 4096 cycles, normal operating mode is entered with the CPU clocked from the crystal frequency (see fig. 1).

The HC12 mode of operation known as Limp-Home Mode (LHM) is enabled when the VDDPLL pin is at VDD and is entered if for any reason the external crystal ceases to oscillate. During this mode the CPU will be clocked from the free-running VCO clock of the PLL (at a nominal frequency of 1MHz). If LHM is enabled during the start-up phase (i.e. VDDPLL=5V, NOLHM bit=0) and the external RESET line is not held active until after the crystal frequency is stable then the device starts up in LHM since no crystal oscillations will be detected. This situation can arise with short reset periods and/or crystals that exhibit slow start-up characteristics.

For the first 4096 cycles i.e. during the internal reset period, Limp Home mode will be de-asserted if oscillator activity is detected by the clock monitor circuit -due to the asserted Reset signal there can be no CPU activity during the Reset phase. Following release of the external or internal POR RESET in LHM (which ever is later) the crystal oscillator is sampled by the clock monitor circuit after another 4096 VCO clock cycles and at intervals of 8192 clock cycles thereafter until the crystal is deemed to be operating. If the crystal oscillator is showing activity at the time it is checked then it will be deemed to be good, even though it may not have fully stabilized, and LHM will be de-asserted. This can cause the device to switch from LH mode to normal mode with the CPU clocked from an unstable signal from the crystal oscillator (see fig. 2) resulting in unpredictable function of the CPU.

The COP Reset doesn't exhibit this behavior as, although the same reset sequence is followed, the oscillator isn't stopped.

When exiting Stop mode (DLY=1) a similar 4096 cycle delay is executed and therefore this behavior could also show up at this time. In applications where this is likely to be an issue, using pseudo-stop is recommended as an alternative. Current draw will increase <math><100 \mu\text{A}</math> at 4MHz in pseudo stop versus stop mode.

Following a loss of external clock in normal operation, Limp Home mode will be entered successfully but if the oscillator is reconnected for some reason a similar situation may arise.

The Reset condition can be overcome by allowing the crystal oscillator circuit to stabilize before releasing the external RESET line (see fig. 3). Operation is similar to that shown in fig 2.

To determine if crystal is 'stable' at the release of reset can be difficult and the time can vary some from board to board. If the customer has special high impedance probes, it is possible to monitor the amplitude of the voltage from XTAL to ground (<math><2 \text{ pF}</math> scope probes are recommended). Please note that any loading on the circuit can affect its operation. (Any resistance to ground or Vdd on the EXTAL pin can greatly attenuate the amplifier gain and cause erroneous operation.)

A second way to measure the oscillator startup time is to monitor the XFC pin. This method does not require a high impedance scope probe. The PLL will not lock until the oscillator clock feeding it is present and stable. Remove the external reset circuit and during power up watch the XFC pin. The voltage should start high (Vdd). After the part releases internal reset it will drop to some stable voltage between Vdd and Vss. If external reset (measured independent from this test) is held till this 'stable voltage' time the oscillator will be stable. Please note the filter components mounted on the XFC pin will affect this ramp (for evaluation purposes, alternative components can be selected to provide a fast lock time). More than one board should be measured because of pcb and crystal variability. It is also recommended that the test be run over the operating temperature of the device.

Lastly, an alternative and simpler approach is to just hold reset low for a substantial time (> 100 milliseconds) after Vdd has reached the operating voltage range.

In some applications it may be possible avoid this issue by delaying the connection of Vddpll to Vdd until the device has exited reset. This will sacrifice the limp home mode safety function upon startup, i.e. the part will no longer be able to start without a functioning crystal. A similar technique (disable PLL under software control) can be used to overcome the limitations of Stop mode.

Limp-Home mode start-up issue

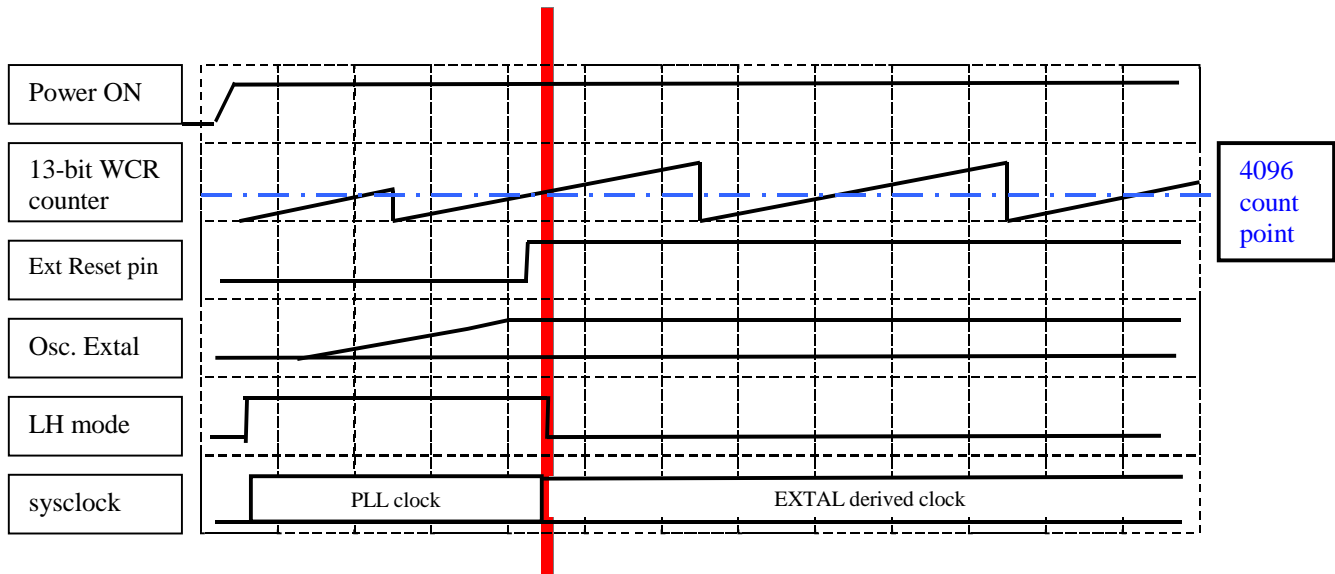


Figure 1. Representation of Normal start-up condition

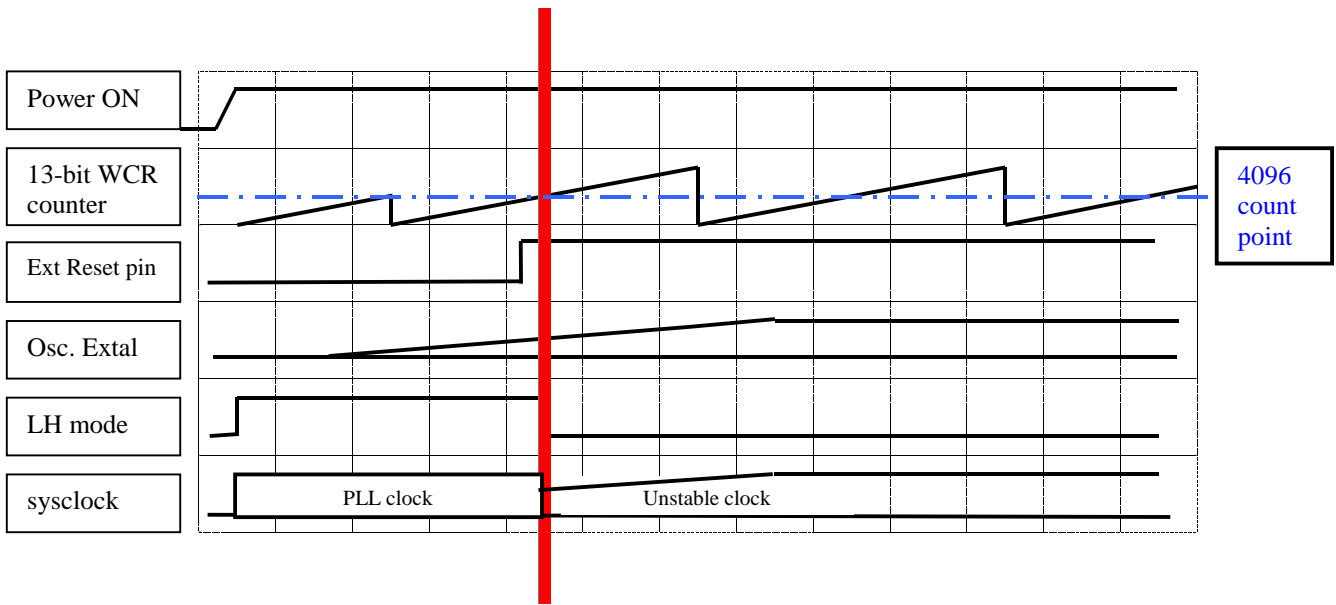


Figure 2. Representation of unreliable start-up mode with slow crystal

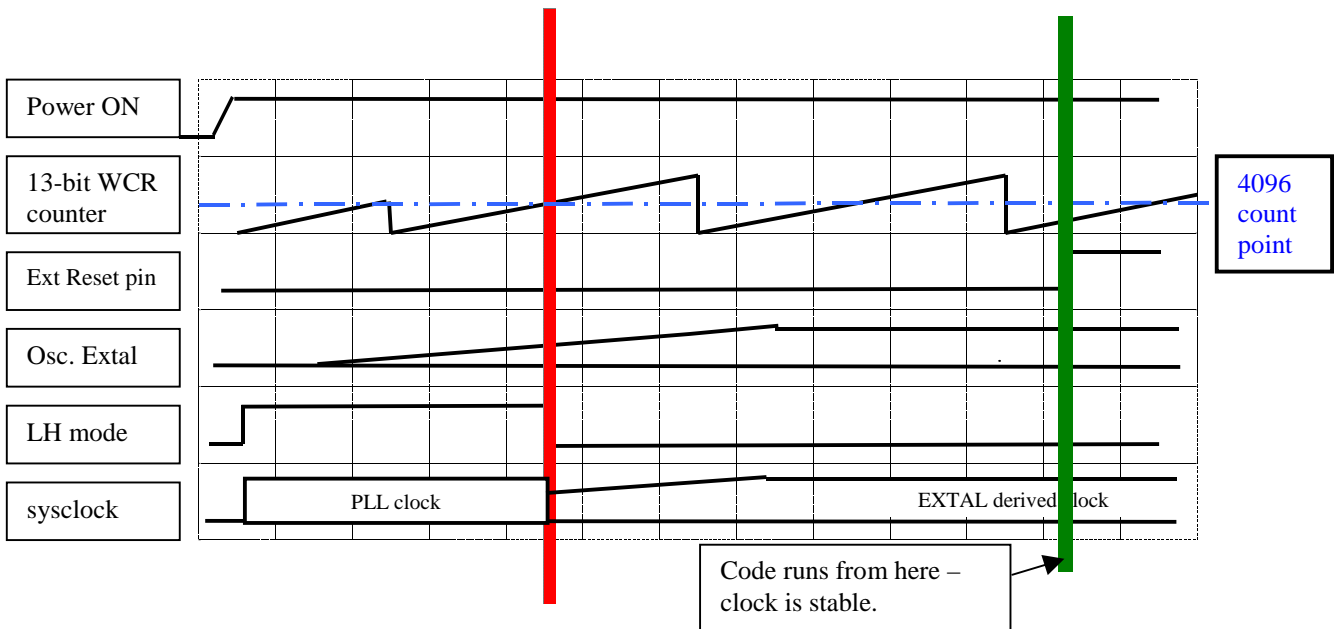


Figure 3. Representation of preferred means of overcoming issue with Figure 2

Errata number	Module affected	Description
AR_636	CGM	Limp home clock frequency is too high

Limp home clock frequency is too high

Errata Number: HC12_AR_636

Description

The typical bus clock frequency in limp home mode is 3 MHz, which is above the maximum specification. The maximum frequency under all operating conditions will be 7.5 MHz until adjustments are made on future versions.

Workaround

Any program code which is frequency dependent during limp home mode should be modified.

Errata number	Module affected	Description
AR_638	WCR/ CGM	Exit from pseudo-stop in limp home

Exit from Pseudo-Stop in Limp Home Mode

Errata Number: HC12_AR_638

Description

If the MCU is operating with the crystal oscillator driving the bus clock (BCSP=0) as it enters pseudo-stop, the chip goes through limp home mode after it wakes up. This is not necessary since the crystal oscillator will be running and available immediately. The limp home bus frequency will not be as accurate as the crystal-driven frequency.

Workaround

N/A

Errata number	Module affected	Description
AR_644	ECT	PA Overflow flag not set when event is concurrent with write of \$FFFF

PA Overflow Flag

Errata Number: HC12_AR_644

Description

When the value \$FFFF is written to PACA or PACB and, at the same time, an external clocking pulse is applied to the PAC, the pulse accumulator may overflow from \$FFFF to \$0000, but the pulse accumulator overflow flag [PAFLG,PBFLG] is not set. Same situation may happen with 8-bit pulse accumulators PAC1 and PAC3.

Workaround

The input capture function for the subject channel be enabled prior to writing a value to the PACA or PACB. Write to the pulse accumulator register. Then do one NOP (to allow the input capture to update the interrupt flag) followed by a read of the input capture interrupt flag to see if it set. If yes, a check must be made for a missing pulse accumulator event. Steps for software workaround to see if event happens while writing to PAC:

1. Enable Input Capture on same pin as the pulse accumulator (and same type of event).
2. Clear the appropriate CxF in the timer interrupt flag register.
3. Read PAC and store as "Old PAC".
4. Calculate desired PAC value and write it to the PAC.
5. Execute 1 NOP.
6. Read CxF in the timer interrupt flag register.

If flag is not set, done (no events happened while writing to the PAC).

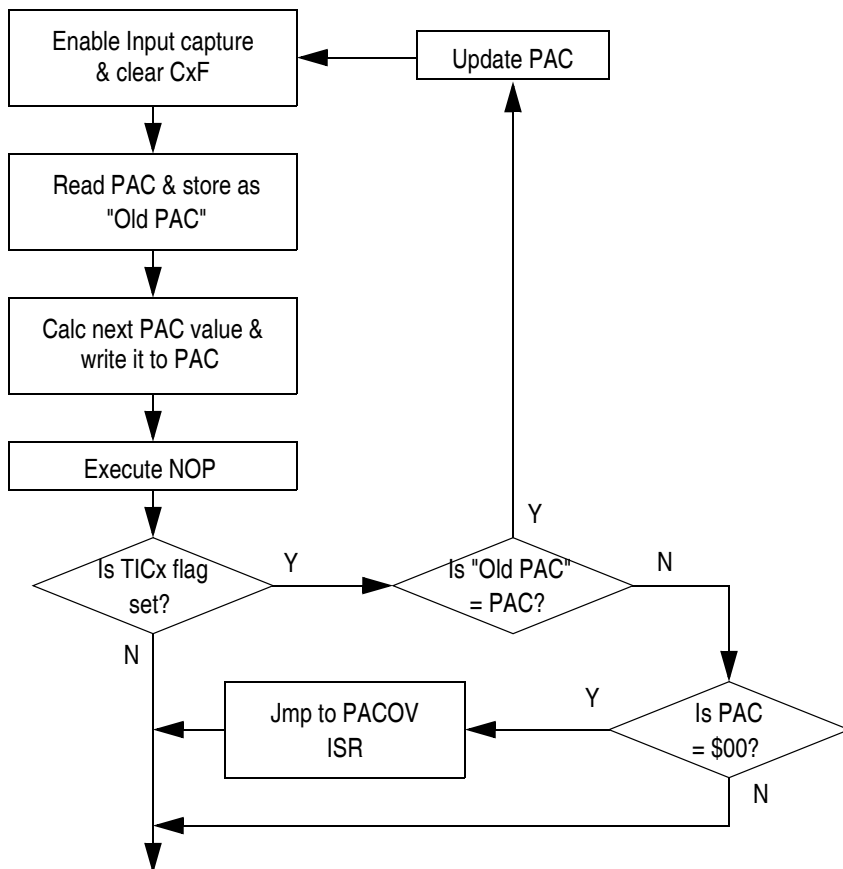
If flag is set read PAC

If "Old PAC" = PAC, then update PAC (event happened while writing to PAC and the PAC did not capture it). Note, if the updated PAC value is \$00 jump to PACOV ISR.

If "Old PAC" does not equal PAC, does PAC = \$00 ?

If yes, jump to PACOV ISR.

If no, done (event happened while writing to the PAC and PAC captured it). Read CxF in the timer interrupt.



Errata number	Module affected	Description
AR_646	MSCAN	MSCAN extended ID rejected if stuff bit between ID16 and ID15

MSCAN Extended ID

Errata Number: HC12_AR_646

Description

For 32-bit and 16-bit identifier acceptance modes, an extended ID CAN frame with a stuff bit between ID16 and ID15 can be erroneously rejected, depending on IDAR0, IDAR1, and IDMR1.

Extended IDs (ID28-ID0) which generate a stuff bit between ID16 and ID15:

IDAR0	IDAR1	IDAR2	IDAR3
*****	***1111x	xxxxxxxx	xxxxxxxx

where x = 0 or 1 (don't care)
* = pattern for ID28 to ID18 (see following).

Affected extended IDs (ID28 - ID18) patterns:

- a. xxxxxxxx01 exceptions: 00000000001
01111100001
xxxx1000001 except 11111000001
- b. xxxxx100000 exception: 01111100000
- c. xxxx01111111 exception: 00000111111
- d. x01111110000
- e. 100000000000
- f. 111111111111
- g. 100000111111

When an affected ID is received, an incorrect value is compared to the 2nd byte of the filter (IDAR1 and IDAR5, plus IDAR3 and IDAR7 in 16-bit mode). This incorrect value is the shift register contents before ID15 is shifted in (i.e. right shifted by 1).

Workaround

If the problematic IDs cannot be avoided, the workaround is to mask certain bits with IDMR1 (and IDMR5, plus IDMR3 and IDMR7 in 16-bit mode).

Example 1: to receive the message IDs

xxxx xxxx x011 111x xxxx xxxx xxxx xxxx

IDMR1 etc. must be 111x xxx1, i.e. ID20,19,18,15 must be masked.

Example 2: to receive the message IDs

xxxx 0111 1111 111x xxxx xxxx xxxx xxxx

IDMR1 etc. must be 1xxx xxx1, i.e. ID20 and ID15 must be masked.

In general, using IDMR1 etc. 1111 xxx1, i.e. masking ID20,19,18,SRR,15, hides the problem.

Note:

The wording of the workaround varies depending on whether the errata mentioned is AR562, AR564, AR565, AR566 or AR567. Substitute as necessary, according to errata list.

Errata number	Module affected	Description
AR_650	CGM	XIRQ during last cycle of STOP instruction causes run away

XIRQ during last cycle of STOP instruction causes run away

Errata Number: HC12_AR_650

Description

If an XIRQ interrupt occurs during the execution of the STOP instruction with the control bit DLY=0 (located in the INTCR register), the CPU may not run the software code as designed.

Workaround

1. Set the delay control bit DLY=1 so that a delay will be imposed prior to coming out of STOP. The user must also implement the workaround for AR_566 (Exiting STOP with DLY=1) as well.
2. If using XIRQ with a stable external clock and DLY=0, contact Motorola Applications Department for a detailed workaround.

Errata number	Module affected	Description
AR_658	CGM	Race condition within Bus Clock Switcher Circuit

Race condition within Bus Clock Switcher Circuit

Errata Number: HC12_AR_658

Description

Under certain conditions it is possible for a race condition to occur within the Bus Clock Switcher Circuit, causing incorrect operation of the CPU. This race condition can occur when the SYSCLK is switched to the PLL clock before the PLI has achieved lock.

Workaround

Do not switch the system clock source to the PLL until the PLL has attained lock.

Errata number	Module affected	Description
AR_659	ATD	Abort in last ATDCLK of sequence does not restart

Abort in last ATDCLK of sequence does not restart

Errata Number: HC12_AR_659

Description

When writing ATDCTL4 and/or ATDCTL5 during an active conversion the write is considered an abort and restart. However, when writing during the last ATDCLK of a sequence, the current conversion is aborted, but a new conversion is not started. This occurs whether the sequence is 1 or 4 or 8 conversions. Since writes to ATDCTL4 start a conversion then it is possible for successive byte writes to ATDCTL4/5 to result in this problem. This would occur if an IRQ service related to another interrupt source occurs, separating the two byte writes, and the RTI of this returns delaying the second write to occur in the last ATDCLK.

Workaround

The first aspect of the solution is to use word writes to ATDCTL4/5. This eliminates the possibility of other IRQ sources causing delay between writes to ATDCTL4/5. This would be the only solution required when starting the first conversion. It would also be the only solution needed when SCAN=0 if all further conversion sequences are initiated from an ATD interrupt routine. In addition, this is the only solution needed if code, in general, does not abort ongoing conversions.

The second aspect to the solution regards cases that abort conversions. The easiest solution is to toggle the S8C bit. This effectively cleans up the abort and the second write to the ATDCTL5 will perform a successful restart. Bracket this toggle sequence with SEI and CLI to prevent the second write from occurring during a last ATDCLK of a sequence.

Another method is possible using dual writes to start a conversion with a minimum of an ATDCLK period between the writes. This effectively allows the first write to abort and flush by the next write which would start (or restart) the conversion. The second write also needs to occur before another sequence complete time elapses. This method should also be prefixed by a SEI and followed by a CLI. This would prevent the case of other IRQ sources causing the same problem as well.

Errata number	Module affected	Description
AR_700	CPU	Asserting an XIRQ interrupt can prevent the CPU from generating the vector request signal for the IRQ

XIRQ interrupt and IRQ

Errata Number: HC12_AR_700

Description

If all of the following conditions are met, the XIRQ asynchronous path can prevent the CPU from generating the vector request signal for the IRQ:

- Using an MCU in the HC12 Family (not the HCS12 Family)
- Using XIRQs (X-bit is cleared in the CCR by software)
- Asserting an XIRQ interrupt (through the XIRQ pin)
- XIRQ interrupt occurs at the start of an IRQ interrupt exception processing

Because XIRQs interrupt IRQs, the XIRQ stack will follow the IRQ stack. The lack of the IRQ vector request signal will cause the XIRQ stack to have an invalid return address. As soon as the XIRQ finishes executing the XIRQ interrupt service routine, the XIRQ RTI (return from interrupt) causes the CPU to use that invalid return address, leading to code runaway.

The potential failure window is only a few nanoseconds and varies with process, temperature, design, etc.

Workaround

There are two identified workarounds: one hardware and one software.

Hardware

Because the failure window is small and occurs near the T1 cycle, the external XIRQ signal could be gated to the rising edge of ECLK.

Software

Because the XIRQ interrupt service routine (ISR) still executes correctly, code can be added to the XIRQ ISR to determine whether the error may have occurred and use software to work around the situation. Because the problem only occurs if the XIRQ interrupts an IRQ before any ISR instructions are executed, the CCR in the XIRQ stack could be checked to determine whether the I-bit was set and two stack frames were created (first one for the IRQ and second one for the XIRQ). Further checks can then be done to determine whether the two stacks are identical except for the return address. If they are, use the IRQ stack as the return address for the XIRQ.

Here is an example of that code:

```

ALL_ISR:
    pshy                ;First instruction of the ALL ISRs need to push something
    inx                 ; (Y for example) onto stack to separate the stack frames
                       ; to help to determine if any instructions from the ISR were
                       ; run. That will determine if the workaround need to be
                       ; done when in the XIRQ ISR.
                       ;Note: this must be done in all ISRs, also adding the inx makes it less likely
                       ; you would falsely think you fell into the erratum. Increment what you tend
                       ; to not use in ISRs first, you could also increment D and Y for even further
                       ; security that the software does not falsely think it fell into the erratum.

                       ;Normal user ISR code here [except no RTI (yet)].

    leas 2,SP          ; return SP to adjust for the pshy

    rti                ; normal user rti

XIRQ_ISR:
                       ;normal user ISR code here [except no RTI (yet)].

    brset 0,SP,#$10,Check;If CCR had I-bit set in the stack, this is the first part
                       ;of the workaround to determine if the XIRQ interrupted
                       ;an IRQ or a section of code that had the I bit set
                       ;If not just return since no problem.

Okrti:
    rti                ;Normal user code (unstack registers, etc.)

Check:
                       ;The I bit was set in the XIRQ stack so we need
                       ; to further check and see if we should do the
                       ; workaround. Need to check to see if there are two
                       ; nearly identical stack frames with the exception of the
                       ; I-bit and the return address. If so adjust the Stack Pointer
                       ; to point to the ISR stack frame before the XIRQ RTI.
                       ;Note, non interruptible code that gets an XIRQ
                       ; will also go here. If X or Y was not used in the XIRQ
                       ; ISR then this code could be reduced in size, (by removing
                       ; the appropriate loads from below)

```

```

ldd 1,SP          ;Load ACCD from XIRQ stack frame ACCB:ACCA value
                  ;Note the values of A and B are interchanged from a
                  ;normal pull for easier checking.
cpd 10,SP         ;Compare ACCD from suspect IRQ stack frame with XIRQ
                  ; stack. Note the values of A and B are still interchanged.
bne Okrti        ;Not the same, so not in erratum, just return (RTI).
ldx 3,SP         ;Load X with XIRQ stack frame X value.
cpx 12,SP        ;Compare X from suspect IRQ stack frame with XIRQ stack.
bne Okrti        ;Not the same, so not in erratum, just return (RTI).
ldy 5,SP         ;Load Y with XIRQ stack frame Y value.
cpy 14,SP        ;Compare Y from suspect IRQ stack frame with XIRQ stack.
bne Okrti        ;Not the same, so not in erratum, just return (RTI).

                  ;Next we check the CCR to see if they are the same except
                  ; for the I bit which should be different.
ldaa 0,SP        ;Load the CCR from the XIRQ stack into ACCA
eora 9,SP        ;Exclusive OR XIRQ CCR with suspect IRQ CCR
anda #$EF       ;AND with the I bit mask to not check the I bit.
bne Okrti        ;Not the same, so not in erratum, just return (RTI).
                  ;if all checks the same could be in the erratum
                  ;could check return address from IRQ ISR as a further check
                  ;to make sure it is a normal ISR program space
                  ;could also check to make sure room for SP to back up
leas 9,SP        ;add 9 to SP (to point to IRQ stack frame)

rti              ;Return using IRQ stack (unstack registers, etc)

```

As with most code workarounds, there are a few situations where there still may be an issue. For example, if you pushed information on to the stack that exactly matched the stack frame before you did the XIRQ and that XIRQ occurred while the I bit was set, the software could falsely think it was the ISR stack. This is a very rare situation.

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